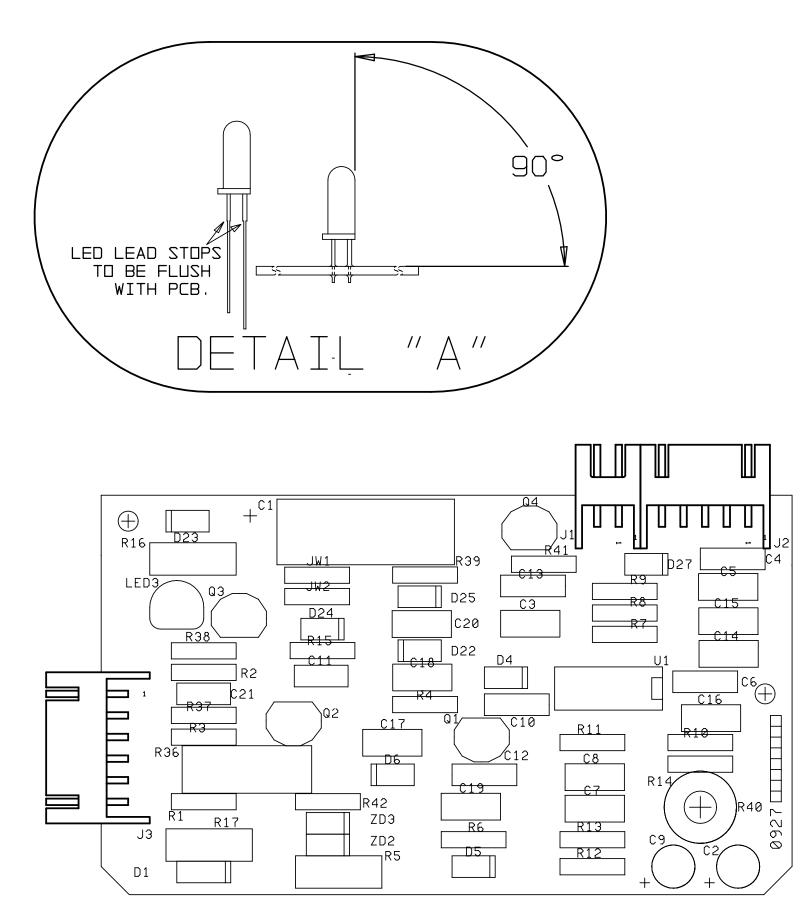


10.	ECD ND.	REVISIONS	DATE⁄BY
C	X	NEW RELEASE	11/25/91 KDH
1	00384	R41 WAS 180K	7/24/92 KDH
2	002049	R16 WAS OPEN	2/8/94 KDH
Ξ	003073	REMOVE D26 R11 WAS 100K R13 WAS 100 R14 WAS 12K C8 WAS .1uF RELABEL JUMPER WIRE AS JW1 RELABEL DLD JW1 AS D1 RELABEL JW2 AS R5	3/5/94 SS
1	002052	NEW BLANK PCB (08270034 R4) ADD JW1, JW2, R42 LED P/N WAS LL2203R	7/14/94 SS
X	003293	DESCRIPTION WAS: PCB,CTRL, CC-16,12VDC,C12MS,INH	8/19/94 SS
5	003365	ADD C14,C15,C16,C17,C18,C19,C20,C21 CHANGE LED3 FROM RED TO GREEN	1/4/95 KDH
×	003810	CHANGE SHEET 2 TO MATCH SILKSCREEN CORRECT SHEET 3	4∕11∕95 KDH
<	\ge	Correct Q3 orentation, correct J1 Pin 1 voltage from 19VDC to 12VDC	2/7/01 BPP

ISMS INC			TITLE PCB,CTRL,CC-16,12VDC, S12MS,INH,SC,NCTL					
IL			DRAWN	KDH	DATE 1/4		′4⁄95	
nd contains pro	oprietary	information	CHKD		DATE			
wing shall be r sed without wri	returned u itten outh	pon request	APP		DATE			
etrimental to t			DWG ND. 09270117				REV 5	
	SIZEB	SCALE X=X	COMP N	D. XXXXXX	XX	SHT 1	0F 1	



NOTES:

- 1. REFER TO SCHEMATIC DIAGRAM AND PARTS LIST FOR
- EXCEPT FOR LED3.
- 4.
- CONTAMINANTS AFTER SOLDERING.
- PROCESS (SEE DETAIL A).
- 7. CONNECTORS TO BE FLUSH TO PCB DURING SOLDERING PROCESS.



TITLE PCB, CTRL, CC-16, 12VDC, CDIN MECHANISMS INC. 400 REGENCY DR. GLENDALE HGTS, IL S12MS, INH, SC, NCTL DRAWN KDH DATE 1/4/95 This drawing is the property of and contains proprietary information of Coin Mechanisms, Inc. The drawing shall be returned upon request and is not to be copied or disclosed without written authorization DATE CHKD APP DATE ^{REV}5 and will not be used in any way detrimental to the interest of Coin DWG ND. 09270117 Nechanisms, Inc. SIZEB SCALE X=X COMP ND. XXXXXXXX SHT 2 DF 3

NO.	ECD ND.	REVISIONS	DATE/BY
5	003365	SEE SHEET 1	4/10/95 KDH

REFERENCE DESIGNATIONS AND COMPONENT VALUES 2. MAXIMUM HEIGHT FOR ANY COMPONENT TO BE .35" 3. MAXIMUM COMPONENT LEAD PROJECTION TO BE .085". SOLDERING SHALL BE IN ACCORDANCE WITH IPC-S-815. 5. ASSEMBLIES TO BE CLEANED OF FLUX AND OTHER 6. LED3 TO BE VERTICAL TO PCB DURING SOLDERING